

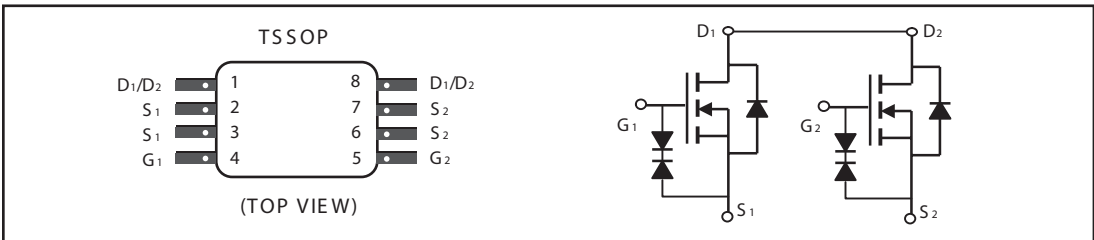


## Dual N-Channel Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY		
V <sub>DSS</sub>	I <sub>D</sub>	R <sub>DS(ON)</sub> (mΩ) Max
20V	10A	13.5 @ V <sub>GS</sub> = 4.0V 18 @ V <sub>GS</sub> = 2.5V

### FEATURES

- Super high dense cell design for low R<sub>DS(ON)</sub>.
- Rugged and reliable.
- Surface Mount Package.
- ESD Protected.



### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	20	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Drain Current-Continuous <sup>a</sup> @ T <sub>J</sub> =25°C -Pulsed <sup>b</sup>	I <sub>D</sub>	10	A
	I <sub>DM</sub>	40	A
Drain-Source Diode Forward Current <sup>a</sup>	I <sub>S</sub>	1.7	A
Maximum Power Dissipation <sup>a</sup>	P <sub>D</sub>	1.5	W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C

### THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Ambient <sup>a</sup>	R <sub>θJA</sub>	85	°C/W
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ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ <sup>c</sup>	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250uA	20			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 16V, V <sub>GS</sub> = 0V			1	uA
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ±12V, V <sub>DS</sub> = 0V			±10	uA
ON CHARACTERISTICS <sup>b</sup>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250uA	0.5	0.8	1.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 4V, I <sub>D</sub> = 5A		11	13.5	m ohm
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 3A		13.5	18	m ohm
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 5A		22		S
DYNAMIC CHARACTERISTICS <sup>c</sup>						
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = 8V, V <sub>GS</sub> = 0V f = 1.0MHz		1815		pF
Output Capacitance	C <sub>OSS</sub>			406		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>			255		pF
SWITCHING CHARACTERISTICS <sup>c</sup>						
Turn-On Delay Time	t <sub>D(ON)</sub>	V <sub>DD</sub> = 10V, I <sub>D</sub> = 1A, V <sub>GEN</sub> = 4V, R <sub>L</sub> = 10 ohm R <sub>GEN</sub> = 10 ohm		31		ns
Rise Time	t <sub>r</sub>			62		ns
Turn-Off Delay Time	t <sub>D(OFF)</sub>			96		ns
Fall Time	t <sub>f</sub>			40		ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 5A, V <sub>GS</sub> = 4V		19		nC
Gate-Source Charge	Q <sub>gs</sub>			3.5		nC
Gate-Drain Charge	Q <sub>gd</sub>			6.7		nC

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## ELECTRICAL CHARACTERISTICS ( $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ <sup>c</sup>	Max	Unit
<b>DRAIN-SOURCE DIODE CHARACTERISTICS<sup>b</sup></b>						
Diode Forward Voltage	$V_{SD}$	$V_{GS} = 0V, I_s = 1.7A$		0.75	1.2	V

### Notes

- a. Surface Mounted on FR4 Board,  $t \leq 10\text{sec}$ .
- b. Pulse Test: Pulse Width  $\leq 300 \mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
- c. Guaranteed by design, not subject to production testing.

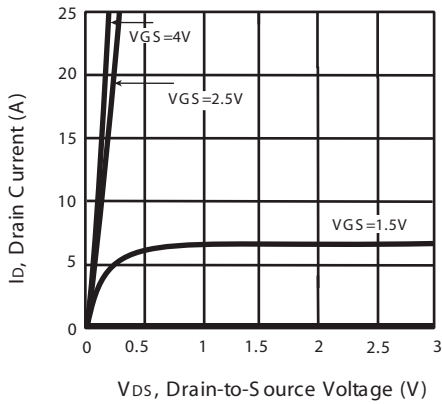


Figure 1. Output Characteristics

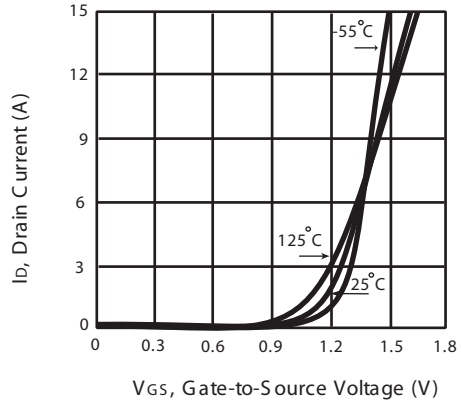


Figure 2. Transfer Characteristics

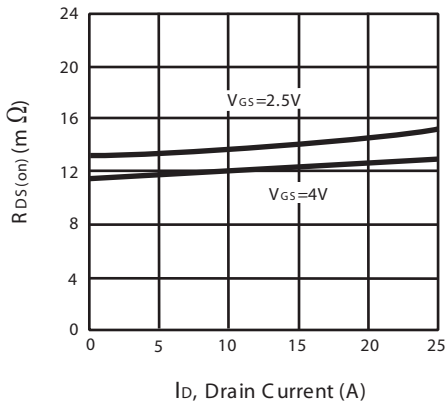


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

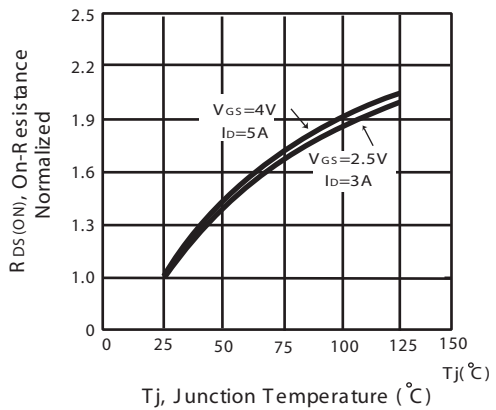


Figure 4. On-R resistance Variation with Drain Current and Temperature

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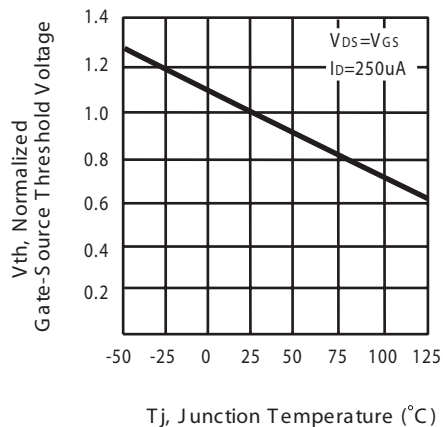


Figure 5. Gate Threshold Variation with Temperature

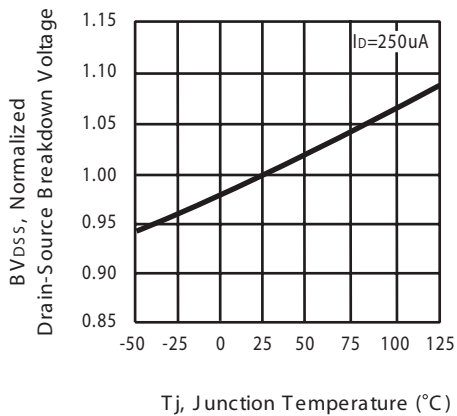


Figure 6. Breakdown Voltage Variation with Temperature

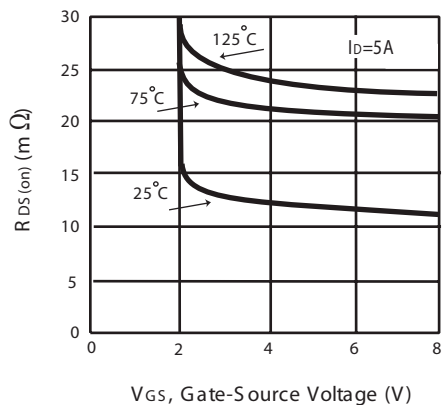


Figure 7. On-Resistance vs. Gate-Source Voltage

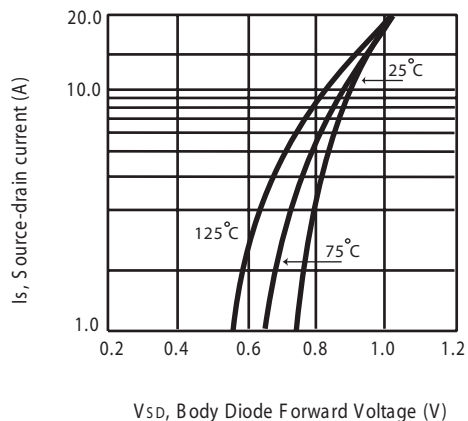


Figure 8. Body Diode Forward Voltage Variation with Source Current

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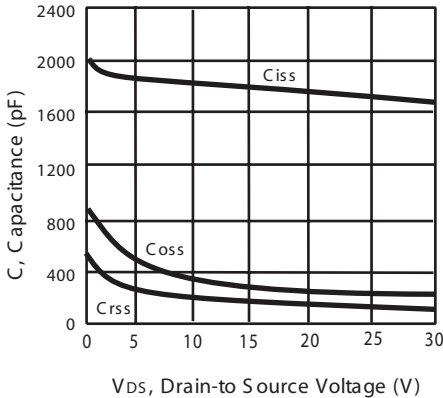


Figure 9. Capacitance

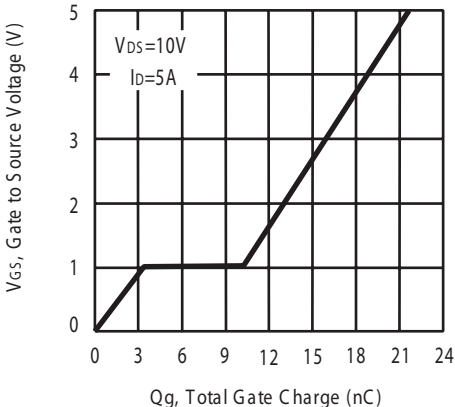


Figure 10. Gate Charge

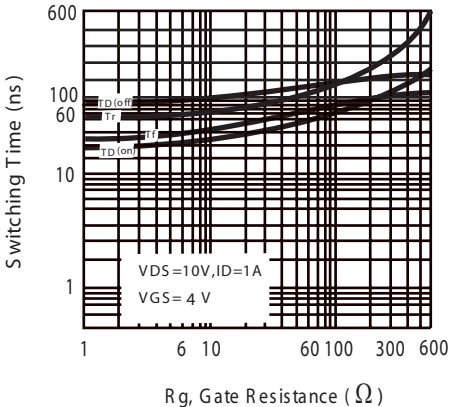


Figure 11. switching characteristics

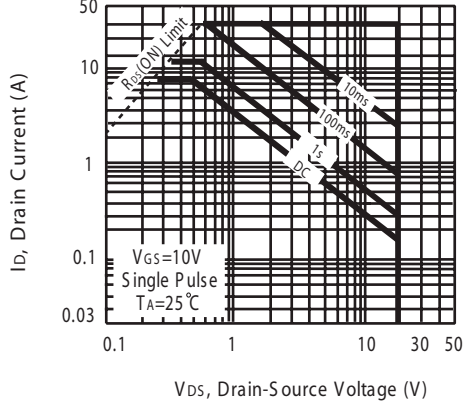


Figure 12. Maximum Safe Operating Area

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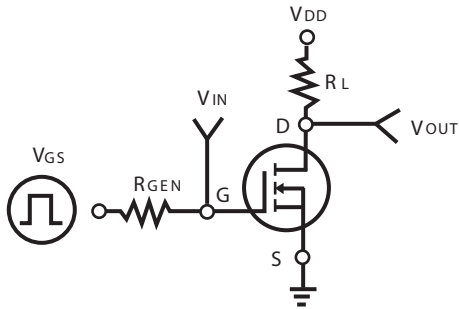


Figure 13. S Switching Test Circuit

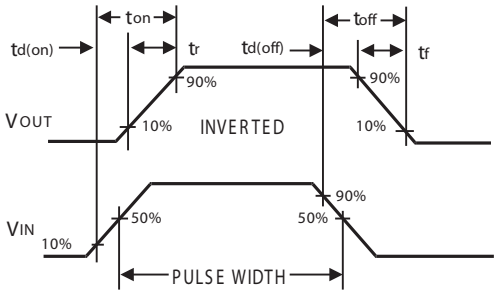


Figure 14. S Switching Waveforms

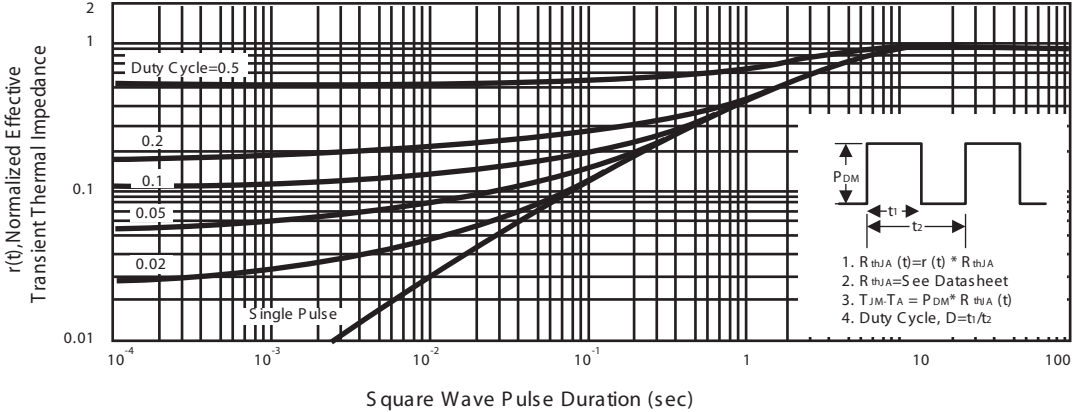
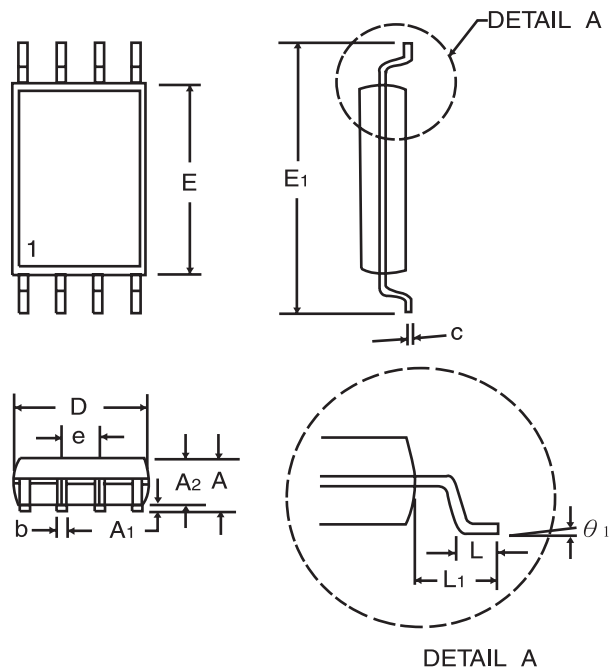


Figure 15. Normalized Thermal Transient Impedance Curve

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## PACKAGE OUTLINE DIMENSIONS

### TSSOP-8

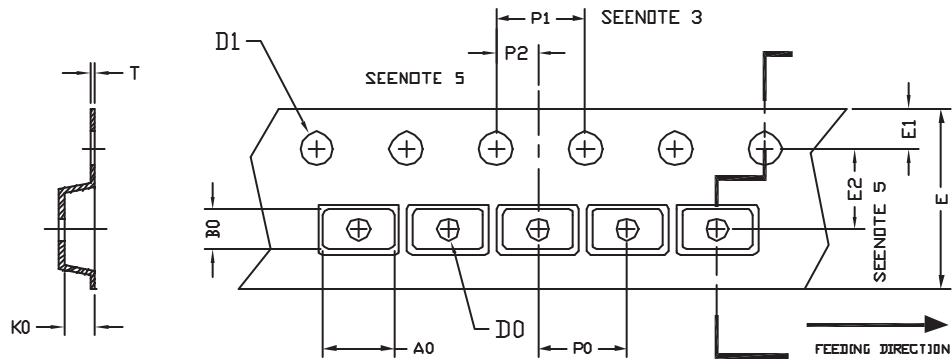


SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.05	1.20	0.041	0.047
A1	0.05	0.15	0.002	0.006
A2	-	1.05	-	0.041
b	0.20	0.28	0.008	0.011
c	0.127		0.005	
D-8	2.90	3.10	0.114	0.122
E	4.30	4.50	0.169	0.177
E1	6.20	6.60	0.244	0.260
e	0.65BSC		0.025BSC	
L	0.50	0.70	0.020	0.028
L1	1.00		0.039	
$\theta_1$	0°	8°	0°	8°

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## TSSOP-8 Tape and Reel Data

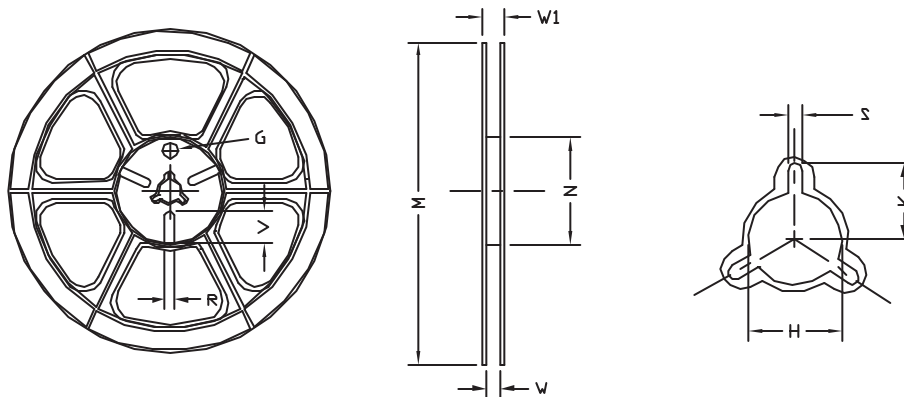
### TSSOP-8 Carrier Tape



UNIT : mm

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
TSSOP 8	6.08	4.40	1.60	$\phi 1.50$ + 0.1 - 0.0	$\phi 1.50$ + 0.1 - 0.0	12.00 $\pm 0.3$	1.75	5.50 $\pm 0.05$	8.00	4.00	2.00 $\pm 0.05$	0.30 $\pm 0.05$

### TSSOP-8 Reel



UNIT : mm

TAPE SIZE	REEL SIZE	M	N	W	W1	H	K	S	G	R	V
12 mm	$\phi 330$	330	100	12.5	16.0	$\phi 13.0$ + 0.5 - 0.2	10.6	2.0 $\pm 0.5$	---	---	---